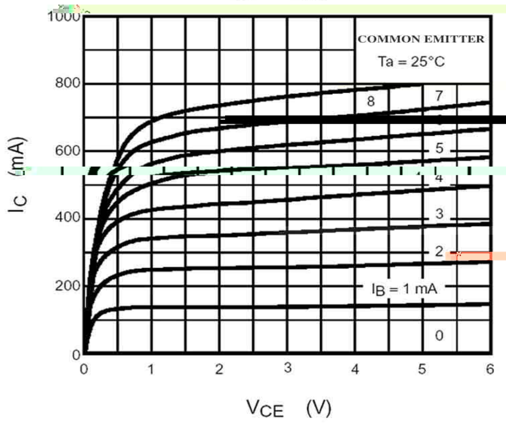
ν ̋Ω Parameter	˧ ᴺ Symbol	̋ΩӪ Rating	ᴅ Ħ Unit
Collector to Base Voltage	V_{CBO}	35	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	800	mA
Emitter Current - Continuous	I_E	-800	mA
Collector Power Dissipation	P_C	600	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

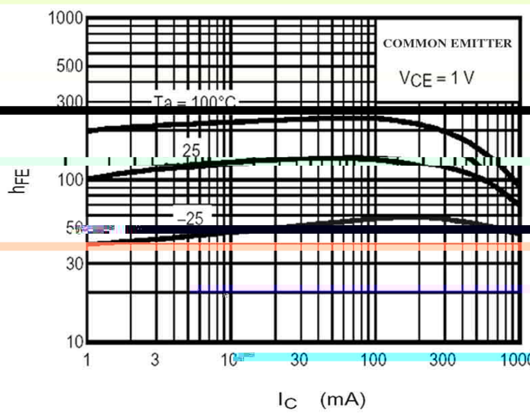
ν ̋Ω Parameter	˧ ᴺ Symbol	╜ ፡ᛏ Ţ Test Conditions	ῳ ṇ Ӫ Min	Ɛ ʒ Ӫ Typ	ῳ ᶻ Ӫ Max	ᴅ Ħ Unit
Collector to Base Breakdown Voltage	V_{CBO}	I_C=10mA I_E=0	30			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=35V I_E=0			0.1	A
Emitter Cut-Off Current	I_{EBO}	V_{EB}=5.0V I_C=0			0.1	A
DC Current Gain	$h_{FE(1)}$	V_{CE}=1.0V I_C=100mA	100		320	
	$h_{FE(2)}$	V_{CE}=1.0V I_C=700mA	35			

/ Electrical Characteristic Curve

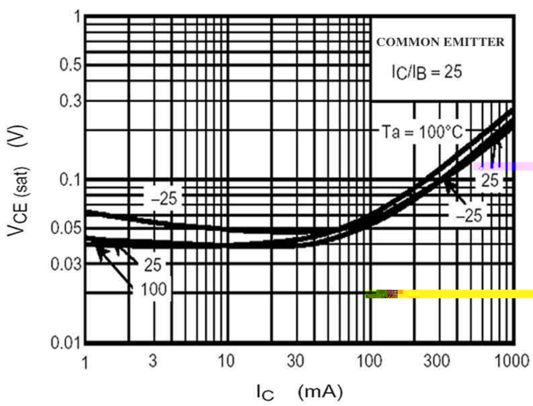
I_C − V_{CE}



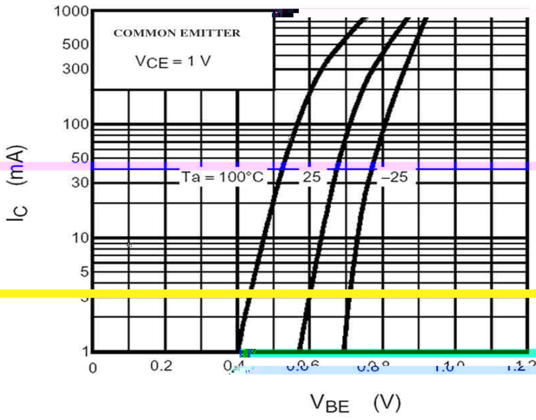
h_{FE} − I_C



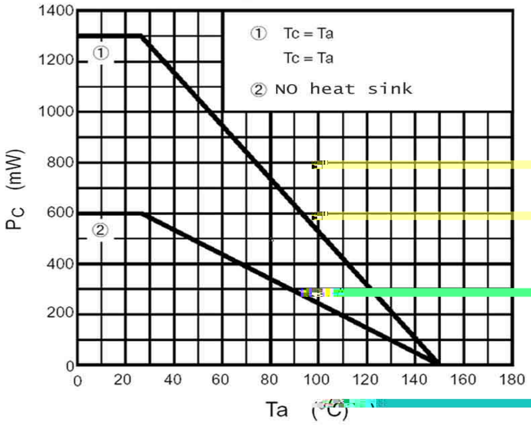
$V_{CE(sat)}$ − I_C



I_C − V_{BE}

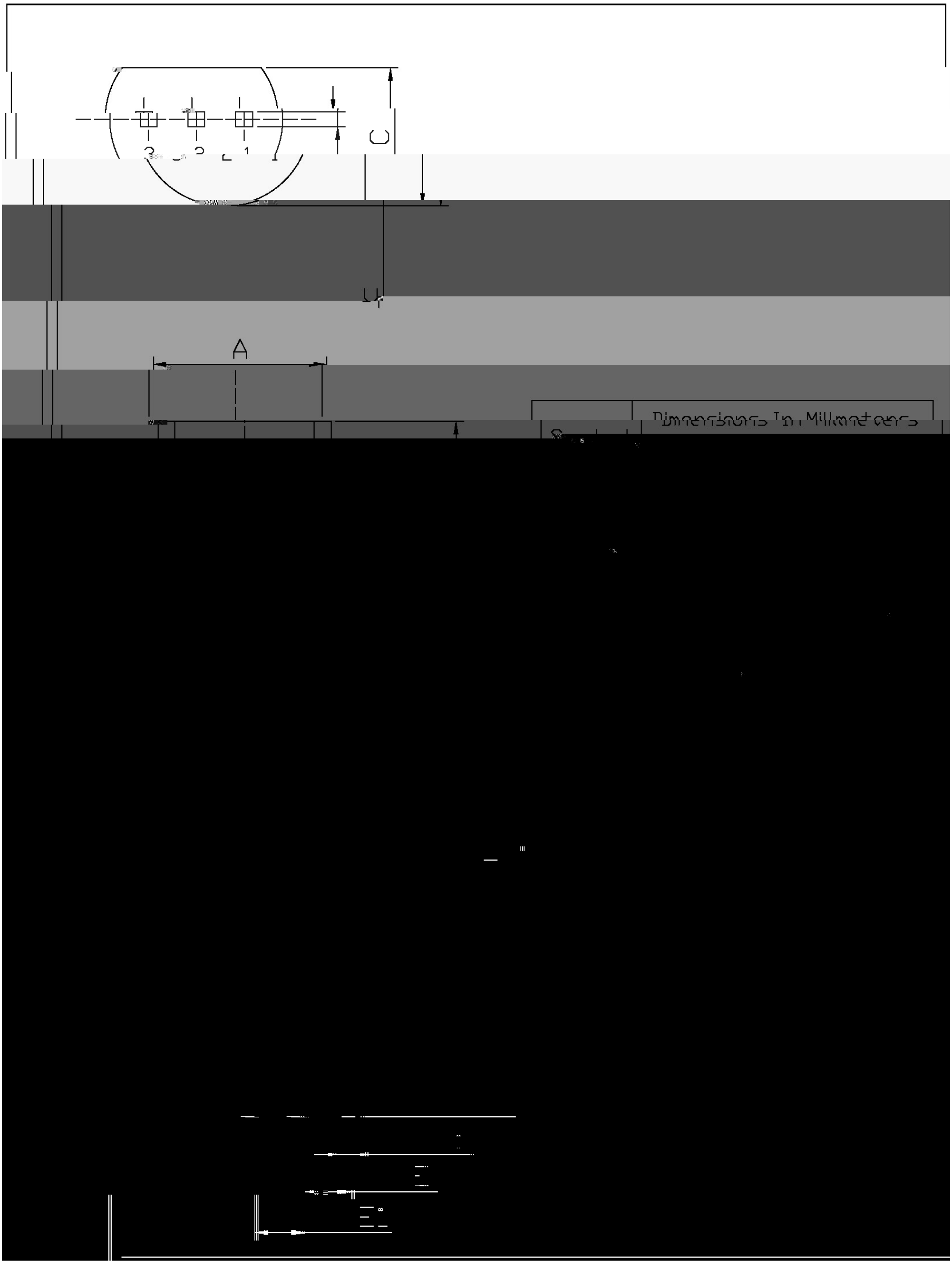


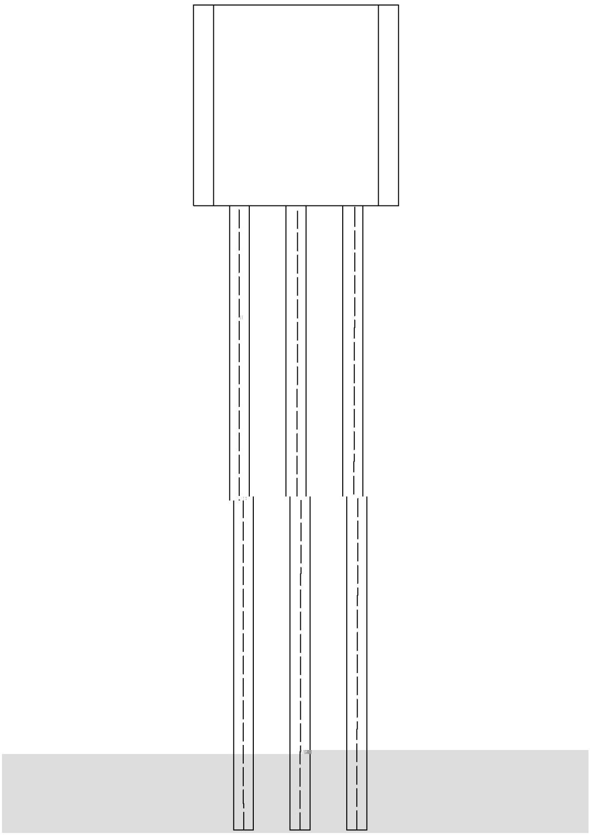
P_C − Ta



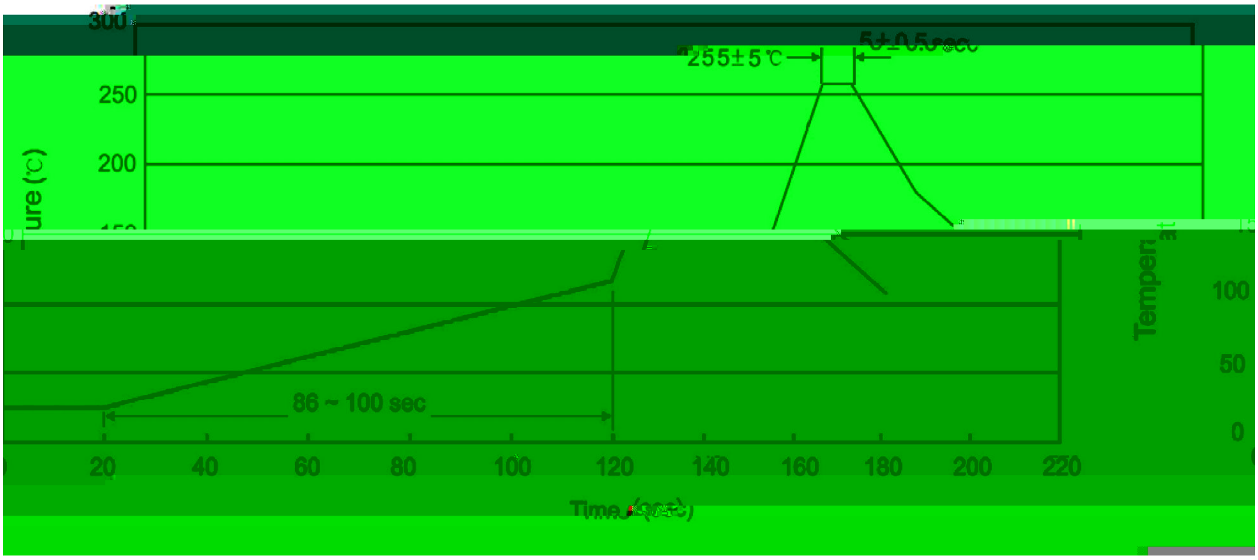
/ Package Dimensions

TO-92 Unit: mm





( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 ἱ ♬ □ ẙ 25 Ḱ 150 ɫ ι `H ڗ 60 Ḱ 90sec;

2 Ś Ӫ □ ẙ 255 ° 5 ɫ ι `H ڗ ʽY ʎ ҥ 5 ° 0.5sec;

3 ὶ ˙ Ⴈ ˛ ɔ ه ẙ ҥ 2 Ḱ 10 ɫ /sec.

Note:

1.Preheating:25~150 ɫ , Time:60~90sec.

2.Peak Temp.:255 ° 5 ɫ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɫ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ẙ χ 270 ° 5 ɫ `H ڗ χ 10 ° 1 sec.

Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

῝Ω ʈ ɣ Ŀ / BULK

Package Type	Units	Dimension	(unit mm3)